

		***	5500 EVB V1.	o i aithot	
tem	Q.ty	Reference	Part	Tech. Characteristics	Package
1	4	C1, C3, C11, C22	10uF/16V	Tantal CAP, 10uF/16V, +/-20%	EIA/IECQ 3216
2		C12	4.7uF/16V	Tantal CAP, 4.7uF/16V, +/-20%	EIA/IECQ 3216
3	3	C13, C26, C32	10nF	25V-20% Ceramic	CASE 0603
4	2	C20, C21	18pF	50V-5% Ceramic	CASE 0603
5		C17	22nF	25V-20% Ceramic	CASE 0603
6	2	C7, C8	22pF	25V-20% Ceramic	CASE 0603
7	2	C18, C25	6.8.nF	50V-10% Ceramic	CASE 0603
8	1	C30	4.7uF	25V-20% Ceramic	CASE 0805
9	1	C24	1nF/2kV	1nF/2kV Ceramic	CASE 1808
10	15	C2, C4, C5, C6, C9, C10, C14, C15, C16, C19, C23, C27, C28, C29, C31	0.1uF	50V-5% Ceramic	CASE 0603
11	2	D1, D2	BAT60A	Silicon Schottky Diode, 10V, 3A	SOD323
12		J1	2pi DC Jack	2pi DC Jack	DCJ0202
13		J2	1.27mm Pin haeder 2x5	1.27mm Pinhaeder 2x5, Male	SMD
14		JP1, JP2	THE VITTING OF EACH	Transmir initiad del Exe, mare	Not Mount
15		JP3			Not Mount
16		1	MI0805K400R-10	Bead for Power Line, 40[ohm]	CASE 0805
17		12	HH-1M1608-121JT	Bead for Power Line, 120[ohm]	CASE 0603
18		LED1	Red LED	CHIP-LED, Red	CASE 0603
19		LED3, LED4	Green LED	CHIP-LED, Green	CASE 0603
20		LED2	LS5050RGB	CHIP-LED, RGB	RGB LED 5050
21		P1	J1B1211CCD	Transformer + RJ45 + LED, Industrial	DIP
22		R1, R14, R15, R38, R39	330R	1/10W-5% SMD	CASE 0603
23		R19, R20, R21, R22, R24, R25, R26, R27, R40	10K	1/10W-5% SMD	CASE 0603
24		R16, R17, R18	10K	1/10W-5% SMD, JUMPER	CASE 0603
25		R29, R31, R32, R33	49R9 1%	1/10W-1% SMD	CASE 0603
26		R30	10R 1%	1/10W-1% SMD	CASE 0603
27		R35	1M	1/10W-5% SMD	CASE 0603
28		R34	12.4K 1%	1/10W-1% SMD	CASE 0603
29		R37	FT-63EP20K	Cermet Trimmers, Top Adjustment, 20K	DIP
		R3	GOEL EGIT	Commercial Top Adjustment, 2010	Not Mount
30		R2, R11, R12	0R	1/10W-5% SMD	CASE 0603
31		R10, R13, R28, R36	22K	1/10W-5% SMD	CASE 0603
32		R4, R5, R6, R9, R23	1K	1/10W-5% SMD	CASE 0603
33		R7, R8	22B	1/10W 5% SMD	CASE 0603
34		S1, S6	ITS-12H(Angle)	Slide SW, Angle Type	DIP
35		S2, S3, S4, S5	SKHMPSE010	Tact SW	SMD
36		TP1, TP2, TP3, TP4, TP5, TP6	GIAI IIVII GEOTO	Tact OVV	Not Mount
37		U4	AT45DB041D-SU	4-Megabit Serial Flash Memory	8S2



Item	Q.ty	Reference	Part	Tech. Characteristics	Package
38	1	U1	AME8815BEGT330	3.3V 1A LDO	SOT-223
39	1	U3	FT232RL	USB to UART	SSOP28
40	1	U3	LPC11E36FHN33/501	NXP Cortex MO MCU	SOT-HVQFN33
41	1	U6	W5500	TCP/IP Chip	QFP48
42	1	U5	TC1047AVNB	Temperature to Voltage Sensor	SOT23
43	1	X1	67503-1030	USB Mini B Type	SMD
44	1	Y1	12MHz(TZ1067B)	X-tal 12MHz,3.2x2.5 SMD, CL=20pF	SMD3225, 4-PAD
45	1	Y2	82J0626-25.000MHz	X-tal 25MHz,3.2x2.5 SMD, CL=18pF	SMD3225, 4-PAD
46	1		2.54mm Pin haeder Socket 1x6	2.54mm Pin haeder Socket 1x6	DIP
47	2		2.54mm Pin haeder Socket 1x8	2.54mm Pin haeder Socket 1x8	DIP
48	1		2.54mm Pin haeder Socket 1x10	2.54mm Pin haeder Socket 1x10	DIP
49	1		PCB	2-Layer, 93mm x 53 mm	